

DESCRIPTION

~~TEMPLATE ASSEMBLY AND METHOD FOR MANUFACTURING TEMPLATE ASSEMBLY~~

TECHNICAL FIELD

[0001]

The present invention relates to a template assembly used in polishing of a surface of workpieces, such as various semiconductor wafers starting with silicon wafers, to hold the workpiece and a method of producing the template assembly.

BACKGROUND ART

[0002]

The apparatuses that can be mentioned as apparatuses for polishing surfaces of a workpiece such as a silicon wafer are a single-side polishing apparatus to polish one surface of the workpiece at a time and a double-side polishing apparatus to polish both surfaces of the workpiece simultaneously. A typical single-side polishing apparatus 200 as shown in FIG. 8 is constituted of a turn table 203 to which a polishing pad 202 is attached, a polishing agent supply mechanism 204, a polishing head 201, and so on. The polishing apparatus 200 holds a workpiece W with the polishing head 201, rotates the turn table 203 and the polishing head 201 while supplying a polishing agent 205 to the polishing pad 202 from the polishing agent supply mechanism 204, and brings a surface of the workpiece W into sliding contact with the polishing pad 202 to polish the workpiece W.

[0003]

DESCRIPTION

TEMPLATE ASSEMBLY AND METHOD OF PRODUCING TEMPLATE

ASSEMBLY

TECHNICAL FIELD

[0001]

The present invention relates to a template assembly used in polishing of a surface of workpieces, such as various semiconductor wafers starting with silicon wafers, to hold the workpiece and a method of producing the template assembly.

BACKGROUND ART

[0002]

The apparatuses that can be mentioned as apparatuses for polishing surfaces of a workpiece such as a silicon wafer are a single-side polishing apparatus to polish one surface of the workpiece at a time and a double-side polishing apparatus to polish both surfaces of the workpiece simultaneously. A typical single-side polishing apparatus 200 as shown in FIG. 8 is constituted of a turn table 203 to which a polishing pad 202 is attached, a polishing agent supply mechanism 204, a polishing head 201, and so on. The polishing apparatus 200 holds a workpiece W with the polishing head 201, rotates the turn table 203 and the polishing head 201 while supplying a polishing agent 205 to the polishing pad 202 from the polishing agent supply mechanism 204, and brings a surface of the workpiece W into sliding contact with the polishing pad 202 to polish the workpiece W.

[0003]